

Abstract

An adhesive sheet composed of a blend of a synthetic rubber S1 and a thermoplastic 2,

a) the blend being microphase-separated,

5 b) the blend possessing at least two softening temperatures, at least one softening temperature being greater than 65°C and less than 125°C,

c) a G' at 23°C, as measured by test method A, of greater than 10^7 Pas,

d) a G" at 23°C, as measured by test method A, of greater than 10^6 Pas,

e) and a crossover, as measured by test method A, of less than 125°C

10 for bonding electrical modules in chip cards.